

Press Release

ATC Introduces New TL MIM Transmission Line Metal-Insulator-Metal Capacitor

September 12, 2014, Huntington Station, NY ----- ATC Thin Film Technologies is pleased to introduce a novel MIM (Metal-Insulator-Metal) capacitor using a transmission line wire bond pad structure with backside ground. This structure provides a unique RF / microwave solution not available from traditional SLC structures.

The TL MIM can be supplied on quartz, alumina, glass and other substrates to minimize losses. Copper traces are used for optimal conductivity. Front and backside gold metalization make this device suitable for epoxy, gold wire bond/ribbon bond attachment techniques.

A data sheet for the TL MIM is available on ATC's website at:

http://www.atceramics.com/UserFiles/TL_MIM.pdf

Features:

- Various substrates for optimized RF/microwave performance
- HFSS optimized design unique for each device
- Copper conductor design for improved circuit conductivity
- Gold wire bondable for high reliability applications
- RoHS Compliant

If you have any questions regarding this product offering, please contact ATC Sales or RF Applications Engineering.



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